L Number	Hits	Search Text	DB	Time stamp
1	370	(257/735).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 08:37
3	136	(257/736).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 08:46
4	1748	(257/758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:43
5	0	("4 and (MCM or (chip on chip or (layered or stacked)))").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:29
7	816	((257/758).CCLS.) and (MCM or (chip on chip or (layered or stacked)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:38
8	575	(((257/758).CCLS.) and (MCM or (chip on chip or (layered or stacked)))) and (MCM or chip on chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:39
9	706	(257/777).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:44
10	0	((257/777).CCLS.) and "cirucuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 09:45
11	278	((257/777).CCLS.) and "circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:12
14	44787	"circuit board" and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:17
15	22360	("circuit board" and chip) and (wiring or pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:17
16	5024	(("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:18
17	3568	((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:18

18	2469	(((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:19
19	2208	((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:19
20	2111	(((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)) and (layer or (layered or (stack or stacked)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:20
21	1959	((((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:21
22	778	(((((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin))) and (tcp or tab)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:22
23	720	((((((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin))) and (tcp or tab)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:28
24	285	(((((((((("circuit board" and chip) and (wiring or pattern)) and (solder and (copper or cu))) and (resin or polyimide)) and (ball or bump)) and (via or hole)) and (layer or (layered or (stack or stacked)))) and (film or (flexible or thin))) and (tcp or tab)) and substrate) and (chip near4 (stack or (stacked or (layer or layered))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/01 10:30

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- (44787) "circuit [Online Documentation]
- (22360) ["circuit board" and chip] and (wiring or pattern)
- (5024) [["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or cu)]
- (3568) [[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or cu)]]...
- (2469) [[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or cu)]...
- (2208) [[[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or cu]...
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- (1959) [[[[[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or c...
- (778) [[[[[[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or c...
- (720) [[[[[[[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or...
- (285) [[[[[[[[[["circuit board" and chip) and (wiring or pattern)] and (solder and (copper or...
- (3) ["5534466"].PN.
- (3) ["4812191"].PN.
- (121) (257/748).CCLS.
- (310) (257/781).CCLS.
- (862) (257/750).CCLS.
- (342) (257/684).CCLS.
- (911) (257/686).CCLS.

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DBs   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM
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	U	☰1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	☐	☐	US 20020079568 A1	20020627	11	Stacked module package	257/686	
2	☐	☐	US 20020079567 A1	20020627	10	PACKAGE STRUCTURE STACKING CHIPS ON FRONT SURFACE AND BACK SURFACE OF SUBSTRATE	257/685	257/686; 257/723;
3	☐	☐	US 20020074639 A1	20020620	9	Semiconductor module with improved solder joint reliability	257/686	257/675; 257/706
4	☐	☐	US 20020074638 A1	20020620	22	MULTI-CHIP SEMICONDUCTOR PACKAGE STRUCTURE	257/686	257/724
5	☐	☐	US 20020074637 A1	20020620	13	Stacked flip chip assemblies	257/686	257/723; 257/737;
6	☐	☐	US 20020070438 A1	20020613	12	Multi-chip stack and method of fabrication utilizing self-aligning electrical contact	257/685	257/686; 257/737;
7	☐	☐	US 20020066952 A1	20020606	17	Semiconductor device having an interconnecting post formed on an	257/698	257/686; 257/701;

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DBs   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   ☐ Plurals

Default operator: OR   ☑ Highlight all hit terms initially

(((((["beam lead" and defin$] and (TCP or (tape or film))] and "circuit board"] and (via or hole)] and metal] and substrate

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	U	⚑1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1.	☐	☐	US 20020041027 A1	20020411	25	Semiconductor device	257/737	438/613
2.	☐	☐	US 20020030261 A1	20020314	7	Multi-flip-chip semiconductor assembly	257/685	438/108
3.	☐	☐	US 20020018101 A1	20020214	21	Inkjet printhead for wide area printing	347/56	
4.	☐	☐	US 20020015073 A1	20020207	21	Inkjet printhead for wide area printing	347/42	
5.	☐	☐	US 20010054756 A1	20011227	13	Multi-layered semiconductor device and method for producing the same	257/678	438/106; 438/121
6.	☐	☐	US 20010053563 A1	20011220	10	Method for manufacturing a chip scale package having slits formed on a substrate	438/106	438/127; 438/613
7.	☐	☐	US 20010001989 A1	20010531	32	Microelectronic connections with liquid conductive elements	174/52.1	29/835; 29/840;
8.	☐	☐	US 6392143 B1	20020521	30	Flexible package having very thin semiconductor chip, module and multi chip	174/52.4	174/254; 174/260;
9.	☐	☐	US 6388336 B1	20020514	9	Multichip semiconductor assembly	257/779	257/666; 257/690;
10.	☐	☐	US 6355981 B1	20020312	37	Wafer fabrication of inside-wrapped contacts for electronic devices	257/735	257/693; 257/702;
11.	☐	☐	US 6329607 B1	20011211	20	Microelectronic lead structures with	174/261	228/180.21;

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